

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) Process for assembling at least one micro-structured substrate comprising upper coplanar plane areas and recesses between them, by means of a glue that can bond to these upper coplanar plane areas, this process being characterised in that it comprises the following steps:

~~-placing a mask-less grid is placed~~ above the substrate, the mask-less grid having a plurality of uniformly spaced holes extending between a top side and a bottom side of the grid, this grid is coated with glue droplets each of the uniformly spaced holes configured to accept a portion of glue having a dimension substantially equal to a width dimension of a smallest recess in the substrate;[[.]]

~~-coating the top side of the grid with glue;~~ and

~~-pressing a tool which presses on the top side of the grid [[and]] to locally brings this~~  
bring the bottom side of the grid into contact with the substrate, wherein glue passing through the holes only deposit on the ~~the upper coplanar plane areas, so as to deposit the glue droplets as a film of glue on these upper coplanar plane area without said film-glue entering into said recesses,~~ and

~~-the grid is removed;~~

process in which the upper coplanar plane areas are treated before the film of glue droplets is deposited on it, this treatment being designed to adapt the wettability of these areas to the glue.

2. (Original) Process according to claim 1, in which the tool is a doctor blade.

3. (Original) Process according to claim 1, in which this treatment is designed to control spreading of glue droplets on the upper coplanar plane areas.
4. (Original) Process according to claim 1, in which the micro-structured substrate is closed with a closing substrate that is fixed to the upper coplanar plane areas by the glue deposited on them.
5. (Original) Process according to claim 4, in which recesses in the micro-structured substrate comprise areas which are provided with biological probes.
6. (Original) Process according to claim 4, in which the closing substrate comprises areas provided with biological probes, these areas being designed to be positioned facing the recesses in the micro-structured substrate after this micro-structured substrate has been closed.
7. (Original) Process according to claim 4, in which the closing substrate comprises drillings through which a fluid will be added into the recesses in the micro-structured substrate.
8. (Previously Presented) Process according to claim 4, in which a set of micro-structured substrates are collectively fabricated in advance on the same substrate, the upper plane areas of all the micro-structured substrates being coplanar, the film of glue droplets is deposited collectively on all of these upper plane areas, all of the micro-structured substrates are closed by the same closing substrate and the micro-structured substrates thus closed are separated from each other.

9. (Previously Presented) Process according to claim 4, in which a set of micro-structured substrates are collectively fabricated in advance on the same substrate, the upper plane areas of all the micro-structured substrates being coplanar, and a set of closing substrates is fabricated collectively on another substrate, also in advance, the micro-structured substrates and the closing substrates are separated from each other and the micro-structured substrates are closed by the closing substrates after depositing the film of glue droplets on the upper coplanar plane areas of each micro-structured substrate.

10. (Previously Presented) Process according to claim 4, in which each substrate is made from a material chosen from among one or more of glass, silicon or polymers.

11. (Previously Presented) Process according to claim 1, in which at least one recess has a width dimension equal to or less than 100  $\mu\text{m}$ .

12. (Cancelled)

13. (Currently Amended) A method for assembling at least one micro-structured substrate having ~~[[an]]~~ upper coplanar plane areas and ~~[[a]]~~ recesses adjacent to the upper coplanar plane area, the method comprising:

- increasing wettability of the upper coplanar plane areas to accept glue thereon;
- ~~placing an array of glue droplets on a mask-less grid above the substrate, the grid~~  
having a plurality of uniformly spaced holes of same width dimension, the holes extending between a top side and a bottom side of the grid, each of the width dimensions at least substantially equal to a corresponding width dimension of a smallest recess in the substrate;

~~-placing glue on the top side of the grid;~~  
~~wherein a dimension of each glue droplet is substantially equal a width dimension of the recess;~~  
~~-pressing downward on the top side of the grid such that the bottom side comes locally~~  
~~into contact with the upper coplanar plane area substrate such that glue is deposited only[[:]]~~  
~~-depositing the glue droplets on the upper coplanar plane areas via the grid while in~~  
~~contact with the upper coplanar plane area, wherein the glue transfers from the grid to the upper~~  
~~coplanar plane area as a glue film; and~~  
~~-removing the grid away from and out of contact with the upper coplanar plane areas,~~  
~~wherein the glue does not enter any of the recesses.~~

14. (Previously Presented) Method according to claim 13, in which at least one recess has a width dimension equal to or less than 100  $\mu\text{m}$ .
15. (Cancelled)
16. (New) Process according to claim 1 further comprising treating the coplanar plane areas to obtain a desired wettability of the coplanar plane areas of the substrate.
17. (New) Process according to claim 1, wherein the glue applied to the grid is in the form of glue droplets.
18. (New) Process according to claim 1, wherein a predetermined portion of the grid is not aligned with the recesses of the substrate when placed above the substrate.

19. (New) A method for assembling at least one micro-structured substrate having upper coplanar plane areas and recesses adjacent to the upper coplanar plane areas, the method comprising:

- placing a mask-less grid above the substrate, the grid having a plurality of uniformly spaced holes of a same width dimension, the holes extending between a top side and a bottom side of the grid, wherein no hole is larger than a smallest recess in the substrate;

- placing glue on the top side of the grid; and

- pressing downward on the top side of the grid such that the bottom side comes locally into contact with the substrate such that the glue is deposited only on the upper coplanar plane areas and no glue enters any of the recesses.